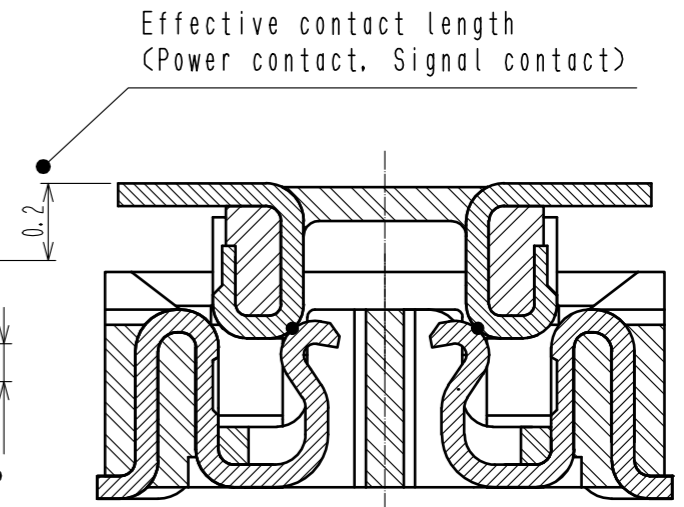
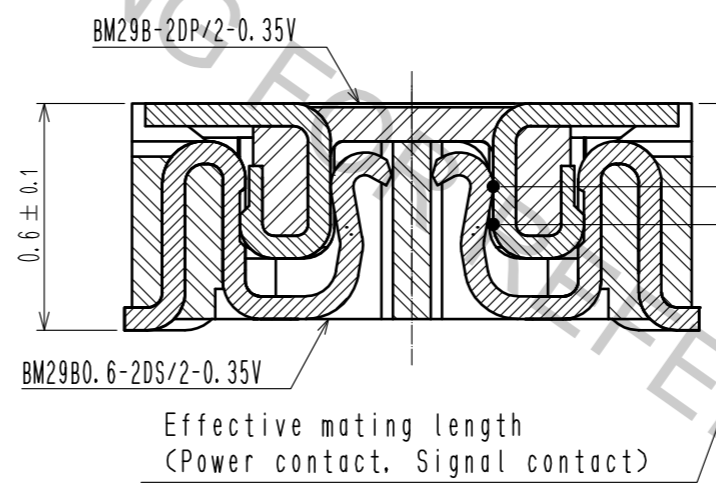
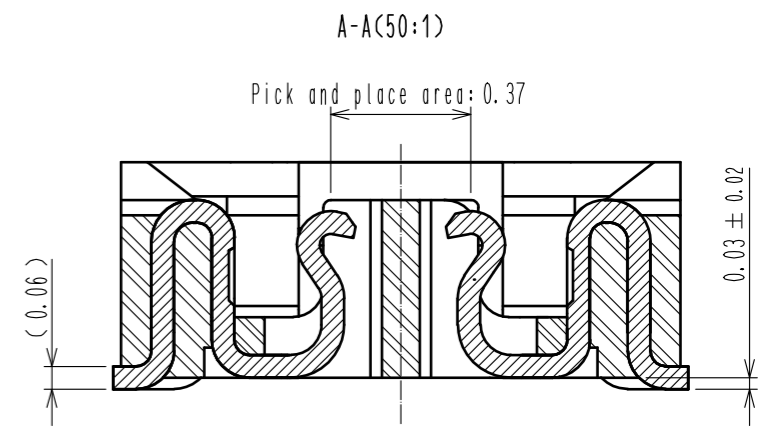
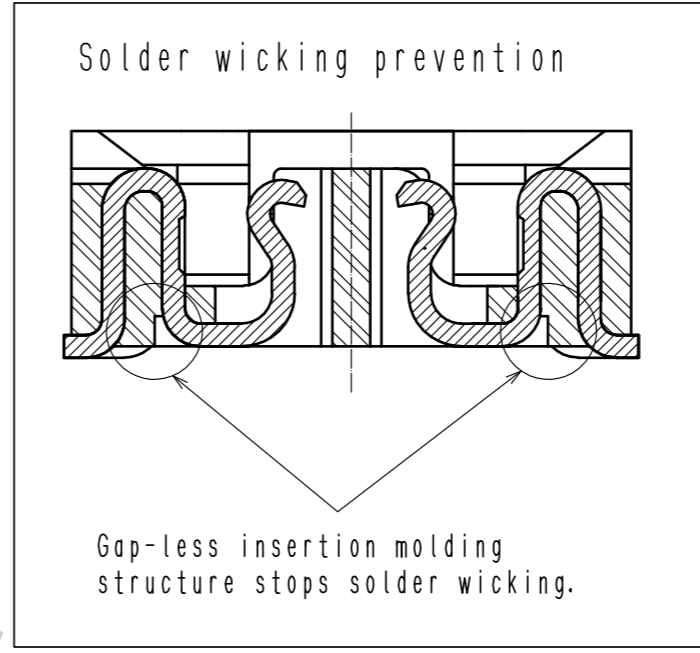


HRS DRAWING REFERENCE

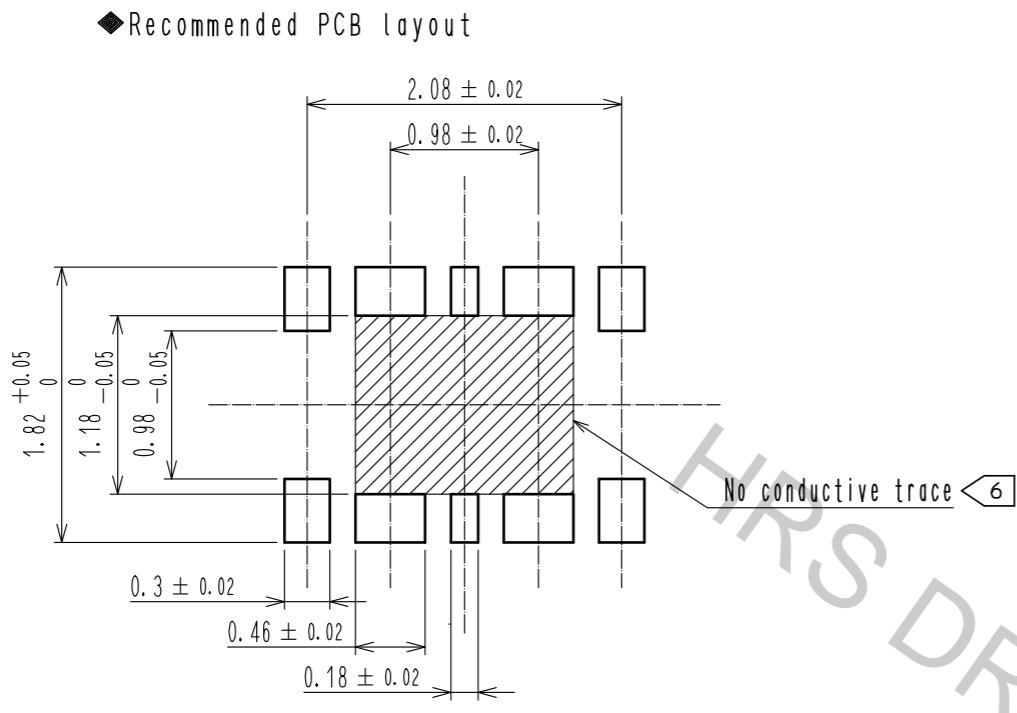


- NOTE 1 . All lead co-planarity shall be 0.08mm MAX.
- ② . Contact plating specifications
 Contact area : Gold 0.05μm MIN
 SMT lead : Gold 0.05μm MIN
 Under plating : Nickel 1μm MIN
 (Surface : Sealing)
 - ③ . HRS mark and CAV No. are indicated in approx. position shown.

NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS
4	PHOSPHOR BRONZE	②		8	PS		CLEAR. REINFORCEMENT COLLAR
3	PHOSPHOR BRONZE	②		7	PS		BLACK. PLASTIC REEL
2	PHOSPHOR BRONZE	②		6	POLYESTER		CLEAR. COVER TAPE
1	LCP		UL94 V-0. BLACK	5	PS		SMOKE GRAY. EMBOSSED CARRIER TAPE

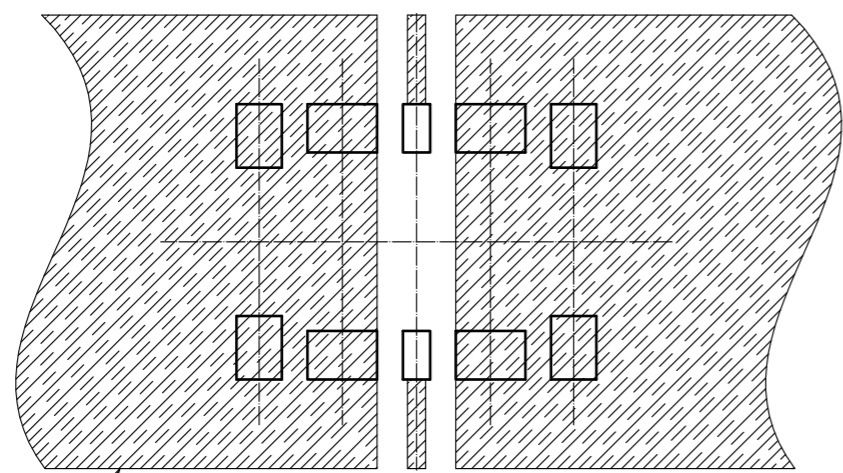
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	20:1	4	DIS-H-00000712	TY. YAMASAKI	WR. FUKUCHI	15.07.13

APPROVED	DATE	DRAWING NO.
MO. ISHIDA	15.03.23	EDC-362699-51-00
CHECKED	DATE	PART NO.
KY. MIDORIKAWA	15.03.23	BM29B0.6-2DS/2-0.35V(51)
DESIGNED	DATE	CODE NO.
TY. YAMASAKI	15.03.23	CL673-7001-0-51
DRAWN	DATE	
TY. YAMASAKI	15.03.23	

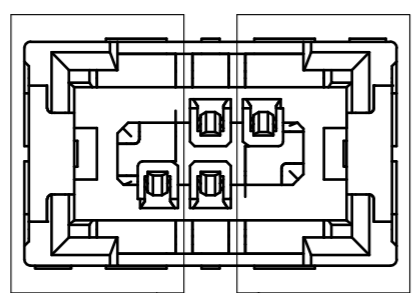


◆ Recommended metal mask dimensions
 Metal mask thickness : 100 μm
 (Open ratio : 100% for PCB layout)

◆ Recommended electrical circuit layout

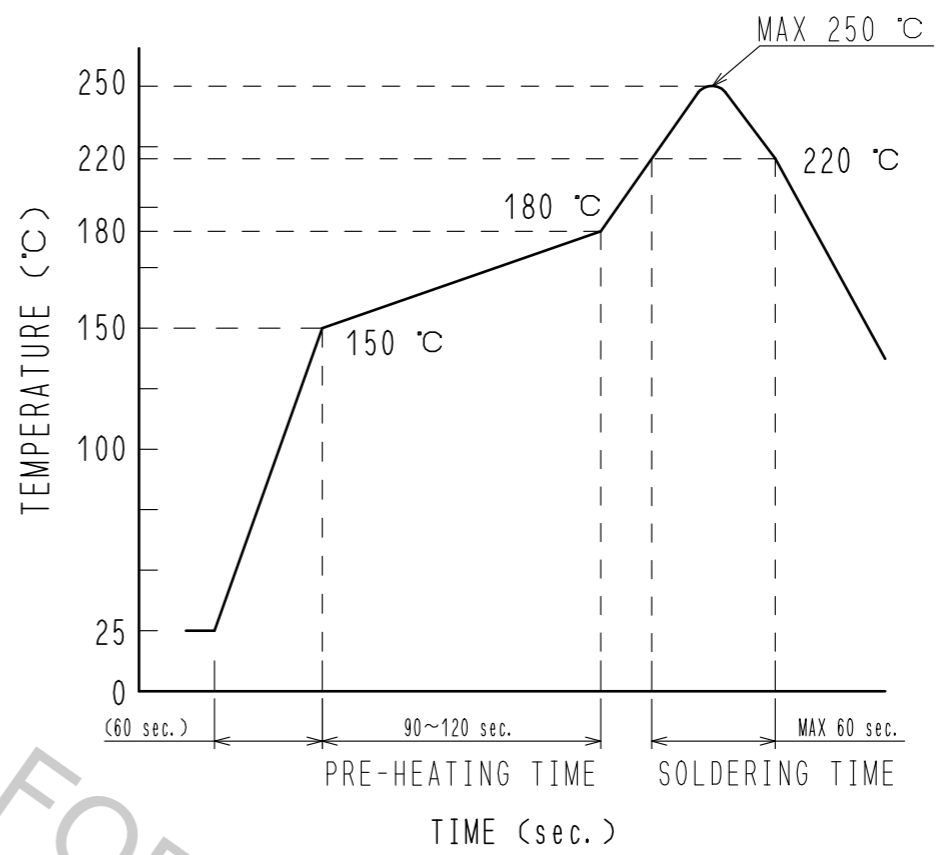


Electrical circuit



Power pin unit

4 Recommended reflow temperature profile using lead-free solder paste.



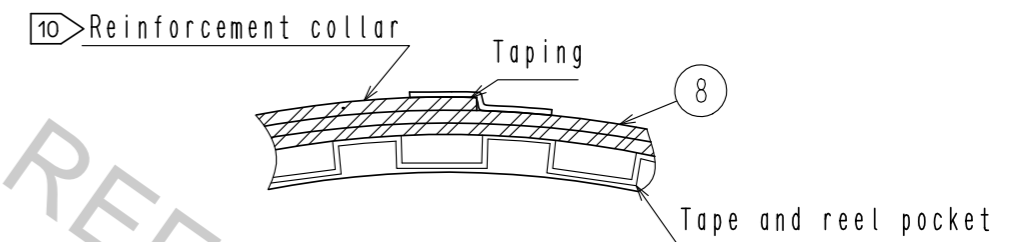
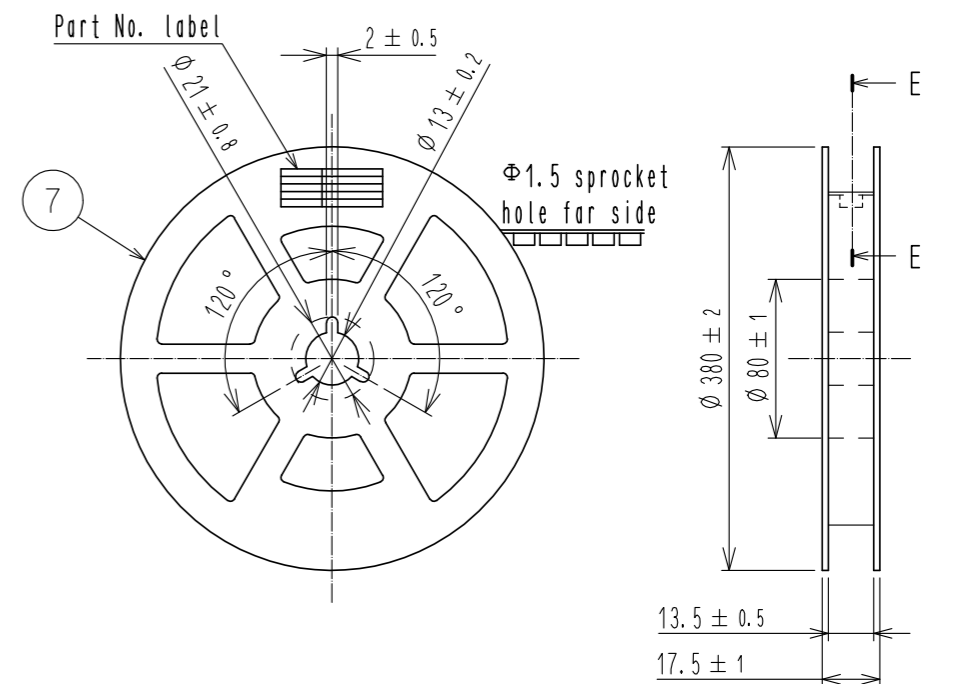
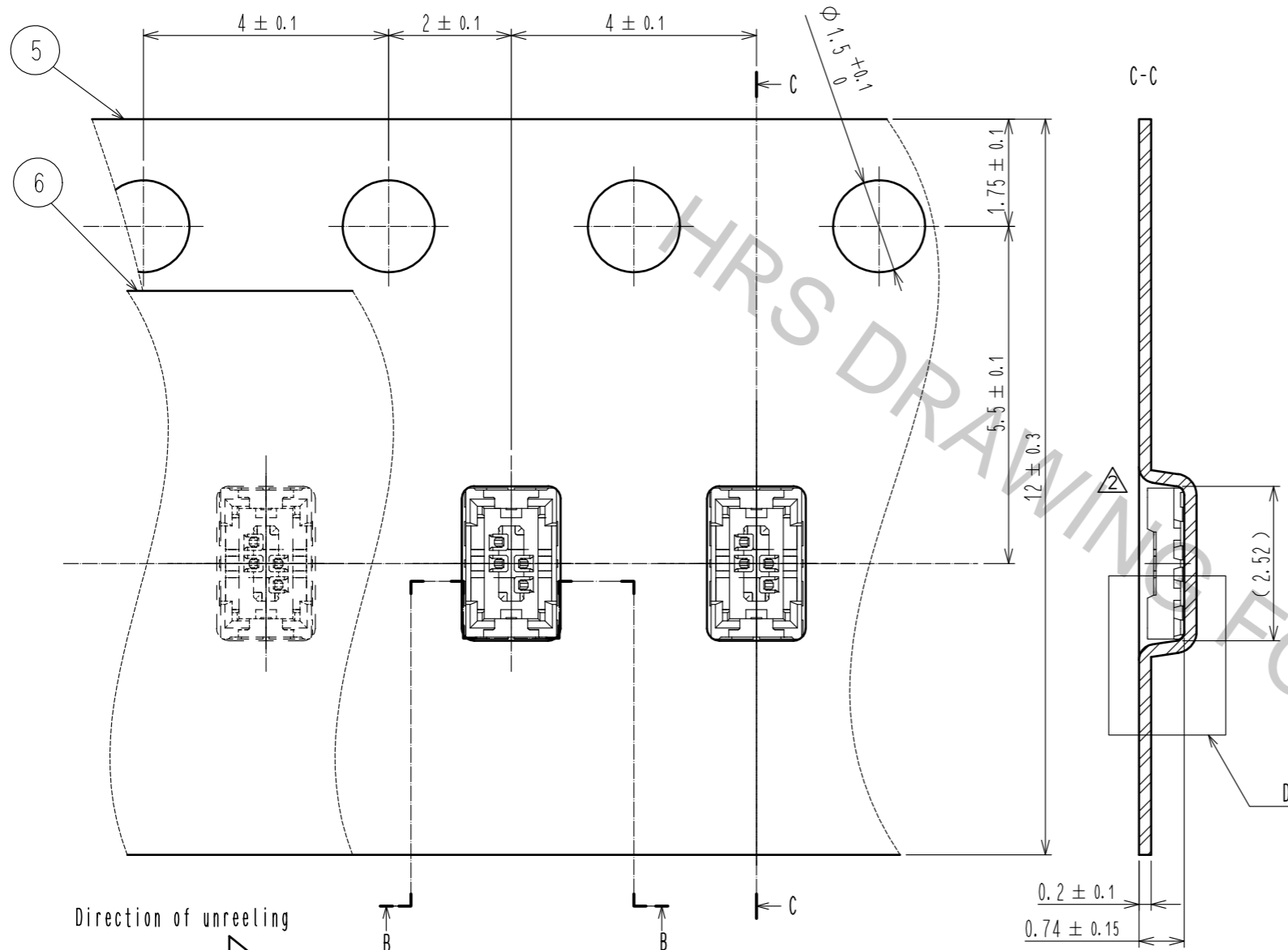
Reflow method: IR reflow
 Number of reflow cycles: 2 cycles MAX.
 1) Reflow time
 Duration above 220°C: 60 sec MAX.
 (Peak temperature: 250°C MAX)
 2) Pre-heat time
 Pre-heat temperature (MIN): 150°C
 Pre-heat temperature (MAX): 180°C
 Pre-heat time: 90-120 sec.

- 4 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
- 5 Please contact us in case you will make different settings from our recommendation.
- 6 For the routing on the indicated PCB surface, apply solder resist in order for the insulation treatment.

HRS	DRAWING NO.	EDC-362699-51-00
	PART NO.	BM29B0. 6-2DS/2-0.35V(51)
	CODE NO.	CL673-7001-0-51
		2/3

Embossed carrier tape packaging (10:1)

Style and dimension of reel (Free)

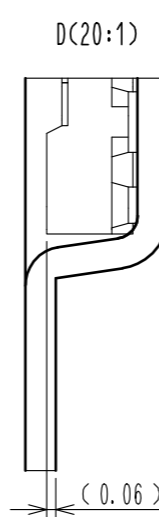
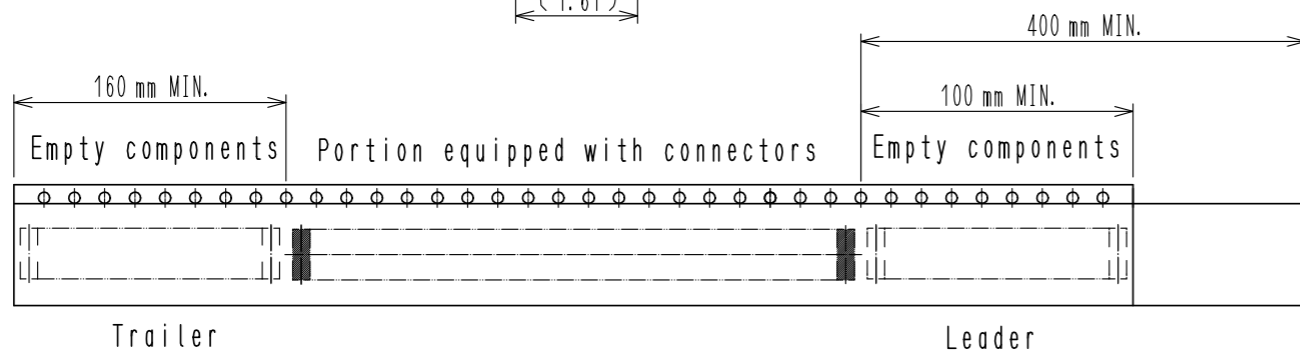


Detail of part No. label

製造年月日	** ** *	Data of manufactured
製品コード	CL0673-7001-0-51	Code No.
製品名	BM29B0.6-2DS/2=0.35V	Part No.
数量	20,000	Quantity
納入者	ヒロセ電機(株)	Supplier

Data of manufactured
Code No.
Part No.
Quantity
Supplier

- 7 . Per reel 20,000 connectors.
- 8 . The dimensions in parentheses are for reference.
- 9 . Refer to JIS C 0806 and IEC60286-3
(Packaging of components for automatic handling)
- 10 . Wrap a reinforcing collar made by polystyrene
to the surface of emboss reel at the termination side
in order to protect emboss carrier tape, top cover tape.



HRS	DRAWING NO.	EDC-362699-51-00	
	PART NO.	BM29B0.6-2DS/2=0.35V(51)	
	CODE NO.	CL673-7001-0-51	3/3